

This listing of claims replaces all prior versions, and listings of claims in the instant application:

Listing of Claims:

1. (Currently amended) A package comprising:
a substrate comprising a pocket;
an electronic component coupled to said substrate within said pocket, said electronic component comprising:
an active area; and
an active calibration area; and
a sensor coupled to said substrate, said sensor comprising a sensor area aligned with said active calibration area.
2. (Original) The package of Claim 1 further comprising a window coupled to said substrate, said active calibration area being position adjacent a first surface of said window directly opposite of a position of said sensor area adjacent a second surface of said window.
3. (Currently amended) A package comprising:
a substrate;
an electronic component coupled to said substrate, said electronic component comprising:
an active area; and
an active calibration area;
a sensor coupled to said substrate, said sensor comprising a sensor area aligned with said active calibration area; and
a window coupled to said substrate, said active calibration area being position adjacent a first surface of said window directly opposite of a position of said sensor area adjacent a second surface of said window, ~~The package of Claim 2~~ wherein said electronic component is located within a pocket of said substrate, said window sealing said pocket.

4. (Original) The package of Claim 3 wherein said window is coupled to said substrate by an adhesive.

5. (Original) The package of Claim 4 wherein said electronic component is within a cavity defined by said window, said adhesive and said pocket.

6. (Original) The package of Claim 3 wherein said pocket is defined by a base and a pocket sidewall, said package further comprising a ground plane coupled to said base.

7. (Original) The package of Claim 6 wherein said electronic component comprises:

a first surface comprising said active area and said active calibration area; and

a second surface coupled to said ground plane and thereby coupled to said substrate.

8. (Original) The package of Claim 6 further comprising a ground pad coupled to said substrate, said ground plane being electrically coupled to said ground pad.

9. (Original) The package of Claim 1 wherein said electronic component is a vertical cavity surface emitting laser (VCSEL) device.

10. (Original) The package of Claim 9 wherein said active area is a first vertical cavity surface emitting laser and wherein said active calibration area is a second vertical cavity surface emitting laser.

11. (Original) The package of Claim 1 wherein said sensor comprises a photodiode.

12. (Currently amended) A package comprising:
a substrate comprising a pocket;
an electronic component coupled to said substrate within
said pocket, said electronic component comprising:
an active area; and
an active calibration area;
a sensor comprising:
a sensor area aligned with said active calibration
area; and
a terminal;
a surface mount pad coupled to said substrate; and
a mounting joint coupling said terminal to said surface
mount pad.

13. (Original) The package of Claim 12 wherein said
mounting joint comprises solder.

14. (Currently amended)
A package comprising:
a substrate;
an electronic component coupled to said substrate, said
electronic component comprising:
an active area; and
an active calibration area;
a sensor comprising:
a sensor area aligned with said active calibration
area; and
a terminal;
a surface mount pad coupled to said substrate;
a mounting joint coupling said terminal to said surface
mount pad; and ~~The package of Claim 12 further comprising~~
a sensor pad coupled to a lower surface of said substrate,
said sensor pad being electrically coupled to said surface
mount pad.

15. (Original) The package of Claim 14 further comprising a sensor via, said sensor pad being electrically coupled to said surface mount pad by said sensor via.

16. (Original) The package of Claim 14 further comprising:

an upper sensor via;
a lower sensor via; and
an interlayer sensor trace, said sensor pad being electrically coupled to said surface mount pad by said upper sensor via, said lower sensor via, and said interlayer sensor trace.

17. (Original) The package of Claim 16 wherein said upper sensor via extends between said surface mount pad and said interlayer sensor trace and wherein said lower sensor via extends between said interlayer sensor trace and said sensor pad.

18. (Original) The package of Claim 12 further comprising a window coupled to said substrate, said active calibration area being position adjacent a first surface of said window directly opposite of a position of said sensor area adjacent a second surface of said window.

19. (Original) The package of Claim 12 wherein said electronic component is a vertical cavity surface emitting laser (VCSEL) device.

20. (Original) The package of Claim 19 wherein said active area is a first vertical cavity surface emitting laser and wherein said active calibration area is a second vertical cavity surface emitting laser.

21. (Original) The package of Claim 12 wherein said sensor comprises a photodiode.

22. (Currently amended) A package comprising:
a substrate comprising a pocket;
an electronic component coupled to said substrate within said pocket, said electronic component comprising:

a means for emitting a first electromagnetic radiation; and

a means for emitting a second electromagnetic radiation; and

a means for sensing said second electromagnetic radiation coupled to said substrate, said means for sensing comprising a sensor area aligned with said means for emitting a second electromagnetic radiation.

23. (Original) The package of Claim 22 further comprising a means for coupling said means for sensing to said substrate.

24. (Currently amended) A package comprising:
a substrate;
an electronic component coupled to said substrate, The
package of Claim 22 wherein said electronic component is
located within a pocket of said substrate, said electronic
component comprising:

a means for emitting a first electromagnetic radiation; and

a means for emitting a second electromagnetic radiation;

a means for sensing said second electromagnetic radiation coupled to said substrate, said means for sensing comprising a

sensor area aligned with said means for emitting a second electromagnetic radiation; and said package further comprising
a means for sealing said pocket.

25. (Original) The package of Claim 24 wherein said means for sealing is transparent to said first electromagnetic radiation and to said second electromagnetic radiation.

26. (Original) The package of Claim 22 wherein said first electromagnetic radiation is the same as said second electromagnetic radiation.

27. (Original) A method comprising:
coupling an electronic component within a pocket
of a substrate, said electronic component comprising:
an active area; and
an active calibration area;
forming bond wires between bond pads of said electronic component and traces coupled to said substrate;
coupling a window to said substrate to seal said pocket;
and
coupling a sensor to said substrate such that a sensor area of said sensor is aligned with said active calibration area.

28. (Original) The method of Claim 27 further comprising:
emitting a first electromagnetic radiation with said active area; and
emitting a second electromagnetic radiation with said active calibration area.

29. (Original) The method of Claim 28 wherein said window is transparent to said first electromagnetic radiation and to said second electromagnetic radiation.

30. (Original) The method of Claim 28 wherein said second electromagnetic radiation is measured by said sensor.

31. (Original) The method of Claim 28 wherein said first electromagnetic radiation is the same as said second electromagnetic radiation.

32. (Original) The method of Claim 27 wherein said electronic component is a vertical cavity surface emitting laser (VCSEL) device.

33. (Original) The method of Claim 32 wherein said active area is a first vertical cavity surface emitting laser and wherein said active calibration area is a second vertical cavity surface emitting laser.

34. (Original) The method of Claim 27 wherein said sensor comprises a photodiode.

35. (Original) The method of Claim 27 wherein said coupling a sensor to said substrate comprises forming a mounting joint between a surface mount pad coupled to said substrate and a terminal of said sensor.

36. (Original) The method of Claim 35 wherein said forming a mounting joint comprises screening solder paste and reflowing said solder paste to form said mounting joint.

37. (New) The package of Claim 1 wherein said substrate further comprises a shelf extending around a periphery of said pocket.

38. (New) The package of Claim 37 further comprising a window, a periphery of a first surface of said window being coupled to said shelf.

39. (New) The package of Claim 1 wherein said pocket is defined by a base and a pocket sidewall.

40. (New) The package of Claim 39 further comprising:
a ground plane coupled to said base; and
an electrically conductive adhesive coupling said
electronic component to said ground plane.

41. (New) The package of Claim 39 further comprising a lead step along said pocket sidewall.

42. (New) The package of Claim 41 further comprising:
electrically conductive traces coupled to said lead step;
and
bond wires coupling said electrically conductive traces to
bond pads of said electronic component.

43. (New) The package of Claim 42 further comprising an encapsulant enclosing said bond pads, said bond wires and said electrically conductive traces.

44. (New) The package of Claim 43 wherein said encapsulant fills said pocket.